

## PATENT ASSIGNMENT

Electronic Version v1.1  
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SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the Spelling of inventor Min-Ta Lei needs to be corrected to Ming-Ta Lei previously recorded on Reel 030764 Frame 0930. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNORS INTEREST.
CONVEYING PARTY DATA	
Name	Execution Date
Ming-Ta Lei	04/09/2001
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Internal Address:	Science-Based Industrial Park
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State/Country:	TAIWAN
Postal Code:	ROC
PROPERTY NUMBERS Total: 1	
Property Type	Number
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ATTORNEY DOCKET NUMBER:	092977B1C3
NAME OF SUBMITTER:	Heidi K. Zuercher
Signature:	/Heidi K. Zuercher/

Date:

08/12/2013

**Total Attachments: 4**

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**PATENT ASSIGNMENT**

Electronic Version v1.1

Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT												
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Mou-Shiung Lin</td><td>04/09/2001</td></tr><tr><td>Min-Ta Lei</td><td>04/09/2001</td></tr><tr><td>Chuen-Jye Lin</td><td>04/09/2001</td></tr></tbody></table>	Name	Execution Date	Mou-Shiung Lin	04/09/2001	Min-Ta Lei	04/09/2001	Chuen-Jye Lin	04/09/2001					
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<table border="1"><tr><td><b>Name:</b></td><td>Megic Corporation</td></tr><tr><td><b>Street Address:</b></td><td>21 R&amp;D First Road</td></tr><tr><td><b>Internal Address:</b></td><td>Science-Based Industrial Park</td></tr><tr><td><b>City:</b></td><td>Hsin-Chu</td></tr><tr><td><b>State/Country:</b></td><td>TAIWAN</td></tr><tr><td><b>Postal Code:</b></td><td>ROC</td></tr></table>	<b>Name:</b>	Megic Corporation	<b>Street Address:</b>	21 R&D First Road	<b>Internal Address:</b>	Science-Based Industrial Park	<b>City:</b>	Hsin-Chu	<b>State/Country:</b>	TAIWAN	<b>Postal Code:</b>	ROC	
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**PATENT**

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**Date:**

07/10/2013

**Total Attachments: 2**

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**PATENT**

MEGOT-004  
09/837,007

(22)

For ☒ U.S. and/or ☒ Foreign RightsFor ☒ Application or ☐ U.S. PatentBy ☒ Inventor(s) or ☐ Present Owner

## ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

## ASSIGNOR

<p>① <u>Mou-Shiung Lin</u> Type or print name of ASSIGNOR</p> <p><u>28 Ginsan 10th st.,</u> Address</p> <p><u>Hsinchu, Taiwan</u></p> <p><u>USA</u> Nationality</p>	<p>② <u>LEI, MING TA LEI</u> Type or print name of ASSIGNOR</p> <p><u>No. 9 Alley 52 Lane 162</u> Address</p> <p><u>Kao-Tsui Rd. Hsin Chu, Taiwan</u></p> <p><u>R.O.C.</u> Nationality</p>
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## ASSIGNEE:

MEGIC Corporation  
21 R&D First Road  
Science-Based Industrial Park  
Hsin-Chu, Taiwan  
R.O.C.  
Nationality

and the successors, assigns and legal representatives of the ASSIGNEE

(complete one of the following)

- ☒ the entire right, title and interest
- ☐ an undivided \_\_\_\_\_ percent (\_\_\_\_%) interest for the United States and its territorial possessions  
(check the following box if foreign rights are also to be assigned)
- ☒ and in all foreign countries

in and to any and all improvements which are disclosed in the invention entitled:

A Structure And Manufacturing Method Of A Chip Scale Package

**PATENT**  
**REEL: 031003 FRAME: 0722**